

Biosketch

Faculty Name: Pankaj Verma



Areas of Interest:

Optical Fiber Communication, Communication Engineering

Education

- M. Tech, KNIT Sultanpur, (Dr. APJ AKTU, Uttar Pradesh)
- B. Tech, IET Lucknow (UPTU, Lucknow)

Academic/Industrial Experience

1. Assistant Professor, Electronics & Communication Engineering, BBDITM, Lucknow 2019-Present
2. Assistant Professor, Electronics & Communication Engineering, BBDEC, Lucknow, 2015-2019
3. Lecturer / Assistant Professor, Electronics & Communication Engineering, BBDNIIT, Lucknow, 2008-2015
4. Lecturer, Electronics & Communication Engineering, IIET, Bareilly, 2005-2008.

Selected Publications

1. Pankaj Verma, Ruchi Singh, and Prof. Y.K. Mishra on ‘Modified GDI Technique - A Power Efficient Method For Digital Circuit Design’ in International Journal of Electronics and Computer Science Engineering, Volume 2 No. 4, ISSN 2277-1956/ V2N4-1071-1080 published on 8/1/2013. (Citation-25, Global Impact factor-0.765)
2. Pankaj Verma, Ruchi Singh, and Dr. R.K.Singh on ‘IMPROVED SOI DEVICE DESIGN USING SILVACO-TCAD SOFTWARE’ in International Symposium on Recent Trends in Electronics & Communication (ISRTEC 2012), at K.N.I.T., Sultanpur, India, on Nov-8,9 2012.
3. Ruchi Singh, Pankaj Verma and Dr. R.K.Singh on ‘COMPARISION OF FD-SOI AND PD-SOI MOSFET’ in International Symposium on Recent Trends in Electronics & Communication (ISRTEC 2012), at K.N.I.T., Sultanpur, India, on Non-8,9 2012
4. Pankaj Verma, Ruchi Singh, and Dr. R.K.Singh on ‘LOW TEMPERATURE SILICON WAFER- TO-WAFER FUSION BONDING’ in National conference on ACCES-2012, at MMMEC Gorakhpur,India, ISBN NO. 978-93-82062-19-6, Page no. 272-276, on 12-13 April 2012.
5. Pankaj Verma, Ruchi Singh, and Prof. Y.K.Mishra on ‘CHARACTERISTICS OF SOI MOSFETS AND ITS APPLICATIONS’ in National conference on Challenges & Opportunities for Technological Innovation in India (COTII-2013), at Ambalika Institute of Technology & Management, Lucknow,India, on Feb 16, 2013.

6. Ruchi Singh, Pankaj Verma and Dr. R.K.Singh on 'WAFER BONDING WITH INTERMEDIATE LAYERS AND SILICON-GOLD EUTECTIC BONDING FOR MEMS DEVICES' in National conference on ACCES-2012, , at MMMEC Gorakhpur, India, ISBN NO. 978-93-82062-19-6, Page no. 252- 256 on 12-13 April 2012.

Membership:

Member of international Association of Engineers.